ABSTRACT

WATER-PERMEABLE ADHESIVE TAPE

The present invention relates to a water-permeable adhesive tape for processing semiconductor wafers and/or semiconductor related materials comprising at least one base film and an adhesive, wherein said at least one base film possesses perforations and has a cavity ratio of 3.0 to 90%. The water-permeable adhesive tape is in particular suitable for dicing semiconductor wafers and/or semiconductor related materials using laser technology.

Figure : NONE